TITLE OF THE INVENTION

Process for mechanical chemical polishing of a layer in a copper-based material.

TEXT OF THE ABSTRACT

Process for mechanical chemical polishing of a layer in a copper-based material using a polishing composition, characterized in that said polishing composition comprises an aqueous suspension of individualized colloidal silica particles not linked to each other by siloxane bonds, the average diameter of which is comprised between 10 and 100 nm, the pH of the aqueous suspension being comprised between 1 and 5.